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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
TATSUYA SAKUISHI	01/30/2015
YUTAKA UCHIDA	02/02/2015
HIROKI ADACHI	01/28/2015
SAKI EGUCHI	03/23/2015
JUNPEI YANAKA	01/28/2015
KAYO KUMAKURA	01/28/2015
SEIJI YASUMOTO	01/28/2015
KOHEI YOKOYAMA	01/30/2015
AKIHIRO CHIDA	01/30/2015

RECEIVING PARTY DATA

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Street Address:	398, HASE	
City:	ATSUGI-SHI, KANAGAWA-KEN	
State/Country:	JAPAN	
Postal Code:	243-0036	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14621914

CORRESPONDENCE DATA

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NAME OF SUBMITTER: JANELLE A. JACKSON

SIGNATURE:	/Janelle A. Jackson/
DATE SIGNED:	03/24/2015
Total Attachments: 4	
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ASSIGNMENT

For valuable consideration, We, <u>Tatsuya SAKUISHI of Atsugi</u>, <u>Kanagawa</u>, <u>Japan</u>, <u>Yutaka UCHIDA of Atsugi</u>, <u>Kanagawa</u>, <u>Japan</u>, <u>Hiroki ADACHI of Tochigi</u>, <u>Tochigi</u>, <u>Japan</u>, <u>Saki OBANA of Tochigi</u>, <u>Tochigi</u>, <u>Japan</u>, <u>Japan</u>, <u>Japan</u>, <u>Junpei YANAKA of Tochigi</u>, <u>Tochigi</u>, <u>Japan</u>, <u>Kayo KUMAKURA of Tochigi</u>, <u>Tochigi</u>, <u>Japan</u>, <u>Seiji YASUMOTO of Tochigi</u>, <u>Tochigi</u>, <u>Japan</u>, <u>Kohei YOKOYAMA of Fujisawa</u>, <u>Kanagawa</u>, <u>Japan and Akihiro CHIDA of Isehara</u>, <u>Kanagawa</u>, <u>Japan hereby assign to Semiconductor Energy Laboratory Co., Ltd.</u>, a <u>Japanese</u> corporation having a place of business at:

398, Hase, Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and
interest throughout the world in the inventions and improvements which are subject of an application for
United States Patent signed by us this day, entitled <u>LIGHT-EMITTING DEVICE AND PEELING METHOD</u>
filed February 13, 2015 , and assigned U.S. Serial Number 14/621,914 , and we
authorize and request the attorneys appointed in said application to hereafter complete this assignment by
inserting above the filing date and serial number of said application when known; this assignment including
said application, any and all United States and foreign patents, utility models, and design registrations
granted for any of said inventions or improvements, and the right to claim priority based on the filing date of
said application under the International Convention for the Protection of Industrial Property, the Patent
Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we
authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models,
design registrations and like rights of exclusion and for inventors' certificates for said inventions and
improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns,
without further compensation to perform such lawful acts and to sign such further applications, assignments,
Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate
fully this assignment.

Signature	latsuya SAKUISHI
Name:	Tatsuya SAKUISHI
Date:	01/30/2015
Signature	Yutaka Uchida
Name:	Yutaka UCHIDA
Date:	02/02/2015

Signature	Hiroki ADACHI
Name:	Hiroki ADACHI
Date:	01/28/2015
Signature	Sak: EGUCHI
Name:	Saki EGUCHI
Date:	01/28/2015
Signature	Junpei Yanaka
Name:	Junpei YANAKA
Date:	01/28/2015
	. ,
Signature	Kayo KUMAKURA
Name:	Kayo KUMAKURA
Date:	01/28/2015
Signature	SEIGI YASUMUTO
Name:	Seiji YASUMOTO
Date:	01/28/20[5
	71 . 71 .
Signature	Rober Johoyama
Name:	Kohei YOKOYAMA
Date:	1/30/20/5
Signature	Akihiro CHIDA
Name:	Akihiro CHIDA
Date:	1/30/2015

ASSIGNMENT

For valuable consideration, We, <u>Tatsuya SAKUISHI of Atsugi</u>, <u>Kanagawa</u>, <u>Japan</u>, <u>Yutaka UCHIDA of Atsugi</u>, <u>Kanagawa</u>, <u>Japan</u>, <u>Hiroki ADACHI of Tochigi</u>, <u>Tochigi</u>, <u>Japan</u>, <u>Saki EGUCHI of Tochigi</u>, <u>Tochigi</u>, <u>Japan</u>, <u>Japan</u>, <u>Japan</u>, <u>Japan</u>, <u>Japan</u>, <u>Japan</u>, <u>Seiji YASUMOTO of Tochigi</u>, <u>Tochigi</u>, <u>Japan</u>, <u>Kohei YOKOYAMA of Fujisawa</u>, <u>Kanagawa</u>, <u>Japan and Akihiro CHIDA of Isehara</u>, <u>Kanagawa</u>, <u>Japan</u> hereby assign to <u>Semiconductor Energy Laboratory Co., Ltd.</u>, a <u>Japanese</u> corporation having a place of business at:

398, Hase. Atsugi-shi, Kanagawa-ken, 243-0036 Japan

and its successors and assigns (collectively hereinafter called "the Assignee"), the entire right, title and interest throughout the world in the inventions and improvements which are subject of an application for United States Patent signed by us this day, entitled LIGHT-EMITTING DEVICE AND PEELING METHOD, filed February 13, 2015, and assigned U.S. Serial Number 14/621,914, and we authorize and request the attorneys appointed in said application to hereafter complete this assignment by inserting above the filing date and serial number of said application when known; this assignment including said application, any and all United States and foreign patents, utility models, and design registrations granted for any of said inventions or improvements, and the right to claim priority based on the filing date of said application under the International Convention for the Protection of Industrial Property, the Patent Cooperation Treaty, the European Patent Convention, and all other treaties of like purposes; and we authorize the Assignee to apply in all countries in our name or in its own name for patents, utility models, design registrations and like rights of exclusion and for inventors' certificates for said inventions and improvements; and we agree for ourselves and our respective heirs, legal representatives and assigns, without further compensation to perform such lawful acts and to sign such further applications, assignments, Preliminary Statements and other lawful documents as the Assignee may reasonably request to effectuate fully this assignment.

Signature		
Name:	Tatsuya SAKUISHI	
Date:		
Signature		
Name:	Yutaka UCHIDA	
Date:		

Signature	
Name:	Hiroki ADACHI
Date:	
Signature	Saki EGUCHI
Name:	Saki EGUCHI
Date:	03/23/2015
Signature	
Name:	Junpei YANAKA
Date:	
Signature	
Name:	Kayo KUMAKURA
Date:	
Signature	
Name:	Seiji YASUMOTO
Date:	
Signature	
Name:	Kohei YOKOYAMA
Date:	
Signature	
Name:	Akihiro CHIDA
Date:	

RECORDED: 03/24/2015